



93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

4K Microwire®-Compatible Serial EEPROM

Device Selection Table

| Part Number | Vcc Range | ORG Pin | Word Size | Temp Ranges | Packages |
|-------------|-----------|---------|-------------|-------------|-------------------|
| 93AA66A | 1.8-5.5 | No | 8-bit | I | P, SN, ST, MS, OT |
| 93AA66B | 1.8-5.5 | No | 16-bit | I | P, SN, ST, MS, OT |
| 93LC66A | 2.5-5.5 | No | 8-bit | I, E | P, SN, ST, MS, OT |
| 93LC66B | 2.5-5.5 | No | 16-bit | I, E | P, SN, ST, MS, OT |
| 93C66A | 4.5-5.5 | No | 8-bit | I, E | P, SN, ST, MS, OT |
| 93C66B | 4.5-5.5 | No | 16-bit | I, E | P, SN, ST, MS, OT |
| 93AA66C | 1.8-5.5 | Yes | 8 or 16-bit | I | P, SN, ST, MS |
| 93LC66C | 2.5-5.5 | Yes | 8 or 16-bit | I, E | P, SN, ST, MS |
| 93C66C | 4.5-5.5 | Yes | 8 or 16-bit | I, E | P, SN, ST, MS |

Features

- Low power CMOS technology
- ORG pin to select word size for '66C version
- 512 x 8-bit organization 'A' ver. devices (no ORG)
- 256 x 16-bit organization 'B' ver. devices (no ORG)
- Self-timed ERASE/WRITE cycles (including auto-erase)
- Automatic ERAL before WRAL
- Power on/off data protection circuitry
- Industry standard 3-wire serial I/O
- Device status signal (READY/BUSY)
- Sequential READ function
- 1,000,000 E/W cycles
- Data retention > 200 years
- Temperature ranges supported:
 - Industrial (I) -40°C to +85°C
 - Automotive (E) -40°C to +125°C

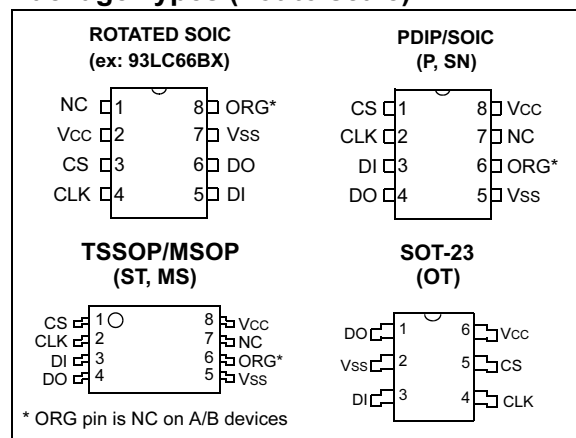
Pin Function Table

| Name | Function |
|------|------------------------|
| CS | Chip Select |
| CLK | Serial Data Clock |
| DI | Serial Data Input |
| DO | Serial Data Output |
| Vss | Ground |
| NC | No internal connection |
| ORG | Memory Configuration |
| Vcc | Power Supply |

Description

The Microchip Technology Inc. 93XX66A/B/C devices are 4K bit low voltage serial Electrically Erasable PROMs (EEPROM). Word-selectable devices such as the 93AA66C, 93LC66C or 93C66C are dependent upon external logic levels driving the ORG pin to set word size. For dedicated 8-bit communication, the 93AA66A, 93LC66A or 93C66A devices are available, while the 93AA66B, 93LC66B and 93C66B devices provide dedicated 16-bit communication. Advanced CMOS technology makes these devices ideal for low power, non-volatile memory applications. The entire 93XX Series is available in standard packages including 8-lead PDIP and SOIC, and advanced packaging including 8-lead MSOP, 6-lead SOT-23, and 8-lead TSSOP. Pb-free (Pure Matte Sn) finish is also available.

Package Types (not to scale)



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93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings†

| | |
|---|--------------------------------|
| V _{CC} | 7.0V |
| All inputs and outputs w.r.t. V _{SS} | -0.6V to V _{CC} +1.0V |
| Storage temperature | -65°C to +150°C |
| Ambient temperature with power applied | -40°C to +125°C |
| ESD protection on all pins | ≥ 4 kV |

†**NOTICE:** Stresses above those listed under “Maximum ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC CHARACTERISTICS

| All parameters apply over the specified ranges unless otherwise noted. | | | V _{CC} = range by device (see Table on Page 1) Industrial (I): T _{AMB} = -40°C to +85°C Automotive (E): T _{AMB} = -40°C to +125°C | | | | |
|--|---------------------------------------|--|--|------|---------------------|-------|---|
| Param. No. | Symbol | Parameter | Min | Typ | Max | Units | Conditions |
| D1 | V _{IH1} | High level input voltage | 2.0 | — | V _{CC} +1 | V | V _{CC} ≥ 2.7V |
| | V _{IH2} | | 0.7 V _{CC} | — | V _{CC} +1 | V | V _{CC} < 2.7V |
| D2 | V _{IL1} | Low level input voltage | -0.3 | — | 0.8 | V | V _{CC} ≥ 2.7V |
| | V _{IL2} | | -0.3 | — | 0.2 V _{CC} | V | V _{CC} < 2.7V |
| D3 | V _{OL1} | Low level output voltage | — | — | 0.4 | V | I _{OL} = 2.1 mA, V _{CC} = 4.5V |
| | V _{OL2} | | — | — | 0.2 | V | I _{OL} = 100 μA, V _{CC} = 2.5V |
| D4 | V _{OH1} | High level output voltage | 2.4 | — | — | V | I _{OH} = -400 μA, V _{CC} = 4.5V |
| | V _{OH2} | | V _{CC} - 0.2 | — | — | V | I _{OH} = -100 μA, V _{CC} = 2.5V |
| D5 | I _{LI} | Input leakage current | — | — | ±10 | μA | V _{IN} = V _{SS} to V _{CC} |
| D6 | I _{LO} | Output leakage current | — | — | ±10 | μA | V _{OUT} = V _{SS} to V _{CC} |
| D7 | C _{IN} , C _{OUT} | Pin capacitance (all inputs/ outputs) | — | — | 7 | pF | V _{IN} /V _{OUT} = 0V (Note 1) T _{AMB} = 25°C, F _{CLK} = 1 MHz |
| D8 | I _{CC} write | Write current | — | — | 2 | mA | F _{CLK} = 3 MHz, V _{CC} = 5.5V |
| | | | — | 500 | — | μA | F _{CLK} = 2 MHz, V _{CC} = 2.5V |
| D9 | I _{CC} read | Read current | — | — | 1 | mA | F _{CLK} = 3 MHz, V _{CC} = 5.5V |
| | | | — | — | 500 | μA | F _{CLK} = 2 MHz, V _{CC} = 3.0V |
| | | | — | 100 | — | μA | F _{CLK} = 2 MHz, V _{CC} = 2.5V |
| D10 | I _{CCS} | Standby current | — | — | 1 | μA | I – Temp |
| | | | — | — | 5 | μA | E – Temp CLK = Cs = 0V ORG = DI = V _{SS} or V _{CC} (Note 2) (Note 3) |
| D11 | V _{POR} | V _{CC} voltage detect 93AA66A/B/C, 93LC66A/B/C 93C66A/B/C | — | 1.5V | — | V | (Note 1) |
| | | | — | 3.8V | — | V | |

Note 1: This parameter is periodically sampled and not 100% tested.

2: ORG pin not available on 'A' or 'B' versions.

3: READY/BUSY status must be cleared from DO, see Section 3.4.

93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

AC CHARACTERISTICS

| All parameters apply over the specified ranges unless otherwise noted. | | | VCC = range by device (see Table on Page 1) Industrial (I): TAMB = -40°C to +85°C Automotive (E): TAMB = -40°C to +125°C | | | |
|--|--------|--------------------------|--|-------------------|-------------------|--|
| Param. No. | Symbol | Parameter | Min | Max | Units | Conditions |
| A1 | FCLK | Clock frequency | — | 3 2 1 | MHz MHz MHz | 4.5V ≤ VCC < 5.5V, 93XX66C only 2.5V ≤ VCC < 5.5V 1.8V ≤ VCC < 2.5V |
| A2 | TCKH | Clock high time | 200 250 450 | — | ns ns ns | 4.5V ≤ VCC < 5.5V, 93XX66C only 2.5V ≤ VCC < 5.5V 1.8V ≤ VCC < 2.5V |
| A3 | TCKL | Clock low time | 100 200 450 | — | ns ns ns | 4.5V ≤ VCC < 5.5V, 93XX66C only 2.5V ≤ VCC < 5.5V 1.8V ≤ VCC < 2.5V |
| A4 | TCSS | Chip select setup time | 50 100 250 | — | ns ns ns | 4.5V ≤ VCC < 5.5V 2.5V ≤ VCC < 4.5V 1.8V ≤ VCC < 2.5V |
| A5 | TCSH | Chip select hold time | 0 | — | ns | 1.8V ≤ VCC < 5.5V |
| A6 | TCSL | Chip select low time | 250 | — | ns | 1.8V ≤ VCC < 5.5V |
| A7 | TDIS | Data input setup time | 50 100 250 | — | ns ns ns | 4.5V ≤ VCC < 5.5V, 93XX66C only 2.5V ≤ VCC < 5.5V 1.8V ≤ VCC < 2.5V |
| A8 | TDIH | Data input hold time | 50 100 250 | — | ns ns ns | 4.5V ≤ VCC < 5.5V, 93XX66C only 2.5V ≤ VCC < 5.5V 1.8V ≤ VCC < 2.5V |
| A9 | TPD | Data output delay time | — | 200 250 400 | ns ns ns | 4.5V ≤ VCC < 5.5V, CL = 100 pF 2.5V ≤ VCC < 4.5V, CL = 100 pF 1.8V ≤ VCC < 2.5V, CL = 100 pF |
| A10 | TcZ | Data output disable time | — | 100 200 | ns ns | 4.5V ≤ VCC < 5.5V, (Note 1) 1.8V ≤ VCC < 4.5V, (Note 1) |
| A11 | Tsv | Status valid time | — | 200 300 500 | ns ns ns | 4.5V ≤ VCC < 5.5V, CL = 100 pF 2.5V ≤ VCC < 4.5V, CL = 100 pF 1.8V ≤ VCC < 2.5V, CL = 100 pF |
| A12 | TWC | Program cycle time | — | 6 | ms | ERASE/WRITE mode (AA and LC versions) |
| A13 | TWC | | — | 2 | ms | ERASE/WRITE mode (93C versions) |
| A14 | TEC | | — | 6 | ms | ERAL mode, 4.5V ≤ VCC ≤ 5.5V |
| A15 | TWL | | — | 15 | ms | WRAL mode, 4.5V ≤ VCC ≤ 5.5V |
| A16 | — | Endurance | 1M | — | cycles | 25°C, VCC = 5.0V, (Note 2) |

Note 1: This parameter is periodically sampled and not 100% tested.

2: This application is not tested but ensured by characterization. For endurance estimates in a specific application, please consult the Total Endurance Model which may be obtained on www.microchip.com.

93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

FIGURE 1-1: SYNCHRONOUS DATA TIMING

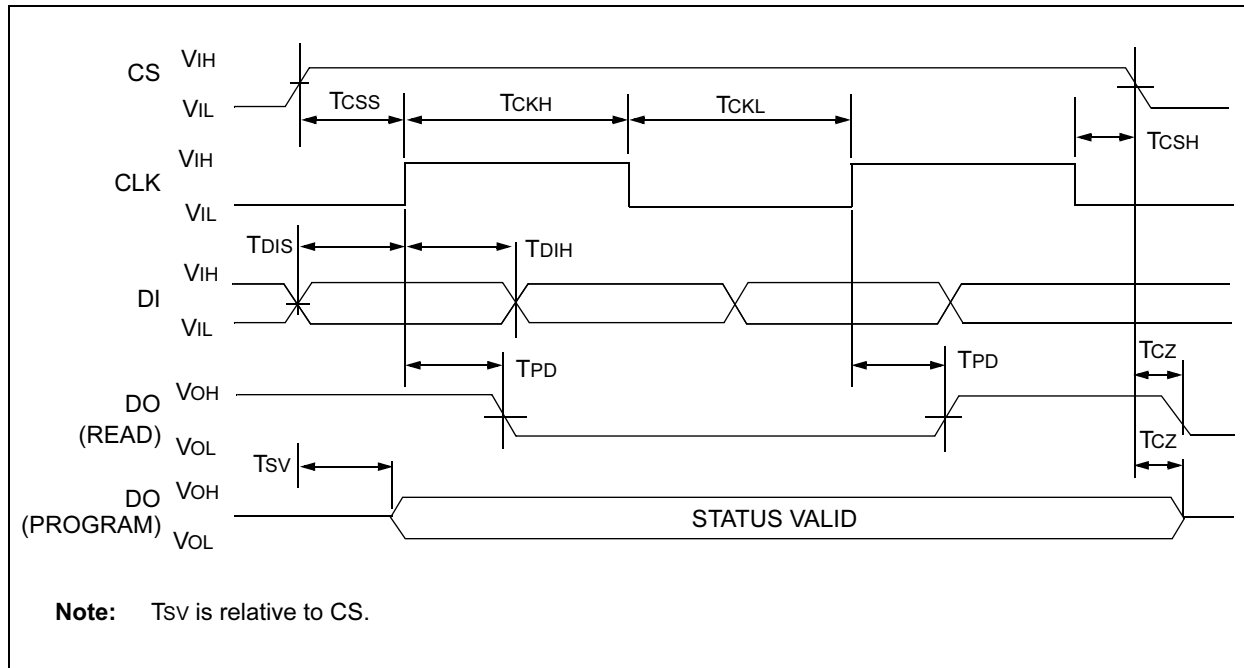


TABLE 1-1: INSTRUCTION SET FOR X 16 ORGANIZATION (93XX66B OR 93XX66C WITH ORG = 1)

| Instruction | SB | Opcode | Address | Data In | Data Out | Req. CLK Cycles |
|-------------|----|--------|-------------------------|----------|---------------------------------|-----------------|
| ERASE | 1 | 11 | A7 A6 A5 A4 A3 A2 A1 A0 | — | (RDY/ $\overline{\text{BSY}}$) | 11 |
| ERAL | 1 | 00 | 1 0 X X X X X X | — | (RDY/ $\overline{\text{BSY}}$) | 11 |
| EWDS | 1 | 00 | 0 0 X X X X X X | — | HIGH-Z | 11 |
| EWEN | 1 | 00 | 1 1 X X X X X X | — | HIGH-Z | 11 |
| READ | 1 | 10 | A7 A6 A5 A4 A3 A2 A1 A0 | — | D15 – D0 | 27 |
| WRITE | 1 | 01 | A7 A6 A5 A4 A3 A2 A1 A0 | D15 – D0 | (RDY/ $\overline{\text{BSY}}$) | 27 |
| WRAL | 1 | 00 | 0 1 X X X X X X | D15 – D0 | (RDY/ $\overline{\text{BSY}}$) | 27 |

TABLE 1-2: INSTRUCTION SET FOR X 8 ORGANIZATION (93XX66A OR 93XX66C WITH ORG = 0)

| Instruction | SB | Opcode | Address | Data In | Data Out | Req. CLK Cycles |
|-------------|----|--------|----------------------------|---------|---------------------------------|-----------------|
| ERASE | 1 | 11 | A8 A7 A6 A5 A4 A3 A2 A1 A0 | — | (RDY/ $\overline{\text{BSY}}$) | 12 |
| ERAL | 1 | 00 | 1 0 X X X X X X X | — | (RDY/ $\overline{\text{BSY}}$) | 12 |
| EWDS | 1 | 00 | 0 0 X X X X X X X | — | HIGH-Z | 12 |
| EWEN | 1 | 00 | 1 1 X X X X X X X | — | HIGH-Z | 12 |
| READ | 1 | 10 | A8 A7 A6 A5 A4 A3 A2 A1 A0 | — | D7 – D0 | 20 |
| WRITE | 1 | 01 | A8 A7 A6 A5 A4 A3 A2 A1 A0 | D7 – D0 | (RDY/ $\overline{\text{BSY}}$) | 20 |
| WRAL | 1 | 00 | 0 1 X X X X X X X | D7 – D0 | (RDY/ $\overline{\text{BSY}}$) | 20 |

93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

2.0 FUNCTIONAL DESCRIPTION

When the ORG* pin is connected to VCC, the (x16) organization is selected. When it is connected to ground, the (x8) organization is selected. Instructions, addresses and write data are clocked into the DI pin on the rising edge of the clock (CLK). The DO pin is normally held in a HIGH-Z state except when reading data from the device, or when checking the READY/BUSY status during a programming operation. The READY/BUSY status can be verified during an Erase/Write operation by polling the DO pin; DO low indicates that programming is still in progress, while DO high indicates the device is ready. DO will enter the HIGH-Z state on the falling edge of CS.

2.1 START Condition

The START bit is detected by the device if CS and DI are both HIGH with respect to the positive edge of CLK for the first time.

Before a START condition is detected, CS, CLK, and DI may change in any combination (except to that of a START condition), without resulting in any device operation (READ, WRITE, ERASE, EWEN, EWDS, ERAL, or WRAL). As soon as CS is HIGH, the device is no longer in Standby mode.

An instruction following a START condition will only be executed if the required opcode, address and data bits for any particular instruction are clocked in.

2.2 Data In/Data Out (DI/DO)

It is possible to connect the Data In and Data Out pins together. However, with this configuration it is possible for a "bus conflict" to occur during the "dummy zero" that precedes the READ operation, if A0 is a logic HIGH level. Under such a condition the voltage level seen at Data Out is undefined and will depend upon the relative impedances of Data Out and the signal source driving A0. The higher the current sourcing capability of A0, the higher the voltage at the Data Out pin. In order to limit this current, a resistor should be connected between DI and DO.

2.3 Data Protection

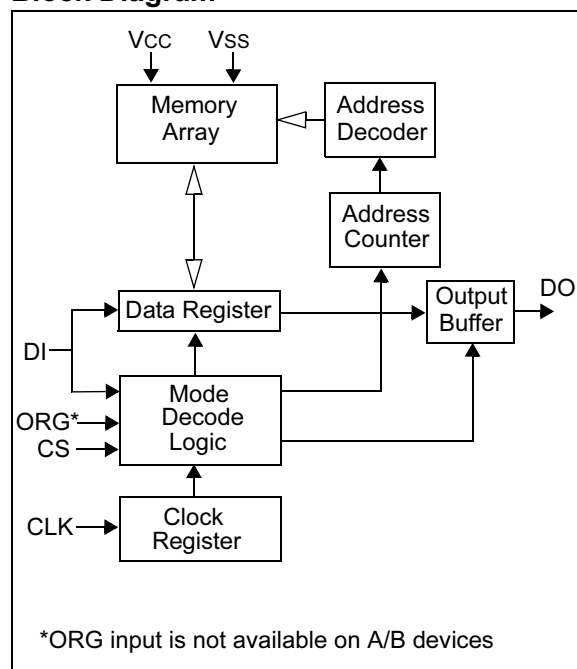
All modes of operation are inhibited when VCC is below a typical voltage of 1.5V for '93AA' and '93LC' devices or 3.8V for '93C' devices.

The EWEN and EWDS commands give additional protection against accidentally programming during normal operation.

Note: For added protection, an EWDS command should be performed after every write operation.

After power-up, the device is automatically in the EWDS mode. Therefore, an EWEN instruction must be performed before the initial ERASE or WRITE instruction can be executed.

Block Diagram



93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

2.4 ERASE

The **ERASE** instruction forces all data bits of the specified address to the logical “1” state. CS is brought low following the loading of the last address bit. This falling edge of the CS pin initiates the self-timed programming cycle, except on ‘93C’ devices where the rising edge of CLK before the last address bit initiates the write cycle.

The DO pin indicates the $\overline{\text{READY}}/\overline{\text{BUSY}}$ status of the device if CS is brought high after a minimum of 250 ns low (T_{CSL}). DO at logical “0” indicates that programming is still in progress. DO at logical “1” indicates that the register at the specified address has been erased and the device is ready for another instruction.

Note: Issuing a START bit and then taking CS low will clear the $\overline{\text{READY}}/\overline{\text{BUSY}}$ status from DO.

FIGURE 2-1: ERASE TIMING FOR 93AA AND 93LC DEVICES

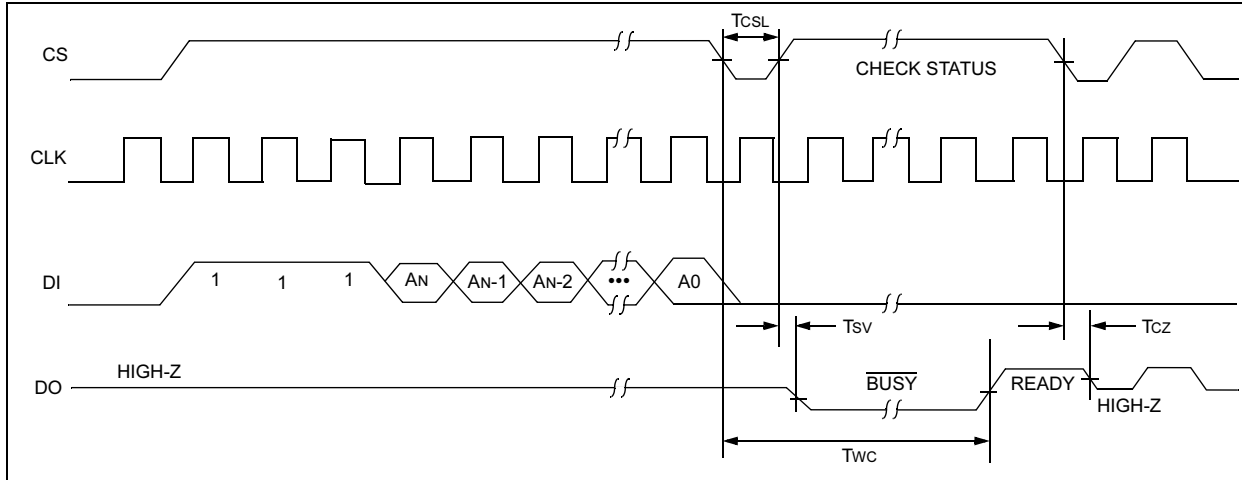
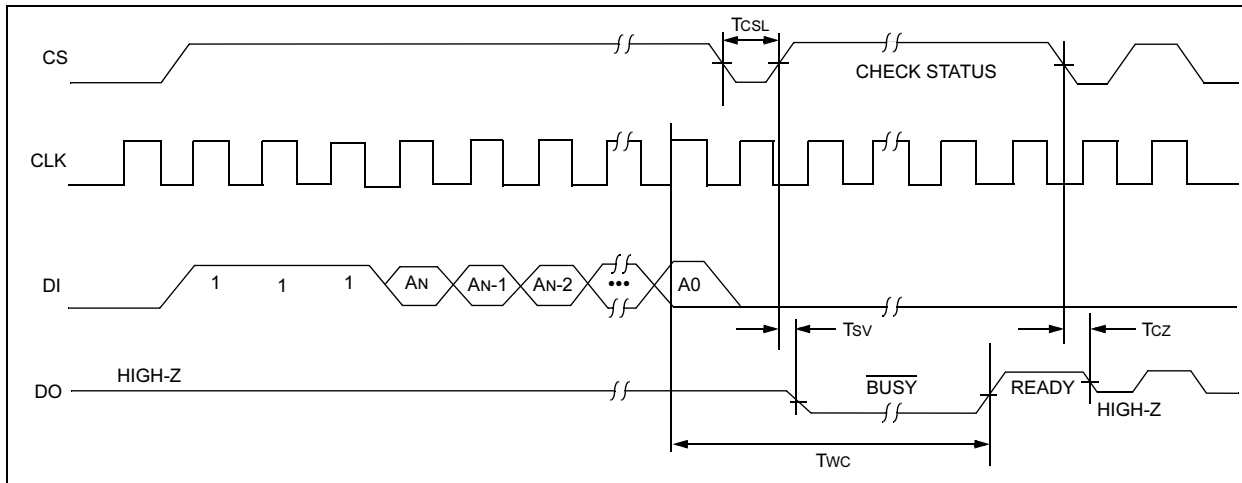


FIGURE 2-2: ERASE TIMING FOR 93C DEVICES



93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

2.5 ERASE ALL (ERAL)

The Erase All (ERAL) instruction will erase the entire memory array to the logical "1" state. The ERAL cycle is identical to the ERASE cycle, except for the different opcode. The ERAL cycle is completely self-timed and commences at the falling edge of the CS, except on '93C' devices where the rising edge of CLK before the last data bit initiates the write cycle. Clocking of the CLK pin is not necessary after the device has entered the ERAL cycle.

The DO pin indicates the READY/ $\overline{\text{BUSY}}$ status of the device, if CS is brought high after a minimum of 250 ns low (T_{CSL}).

Note: Issuing a START bit and then taking CS low will clear the READY/ $\overline{\text{BUSY}}$ status from DO.

VCC must be $\geq 4.5\text{V}$ for proper operation of ERAL.

FIGURE 2-3: ERAL TIMING FOR 93AA AND 93LC DEVICES

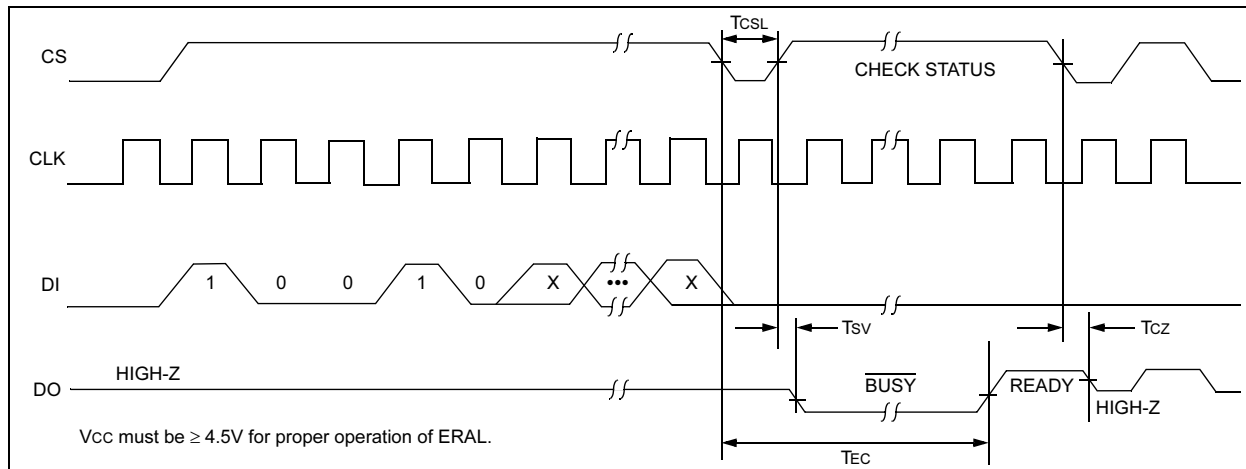
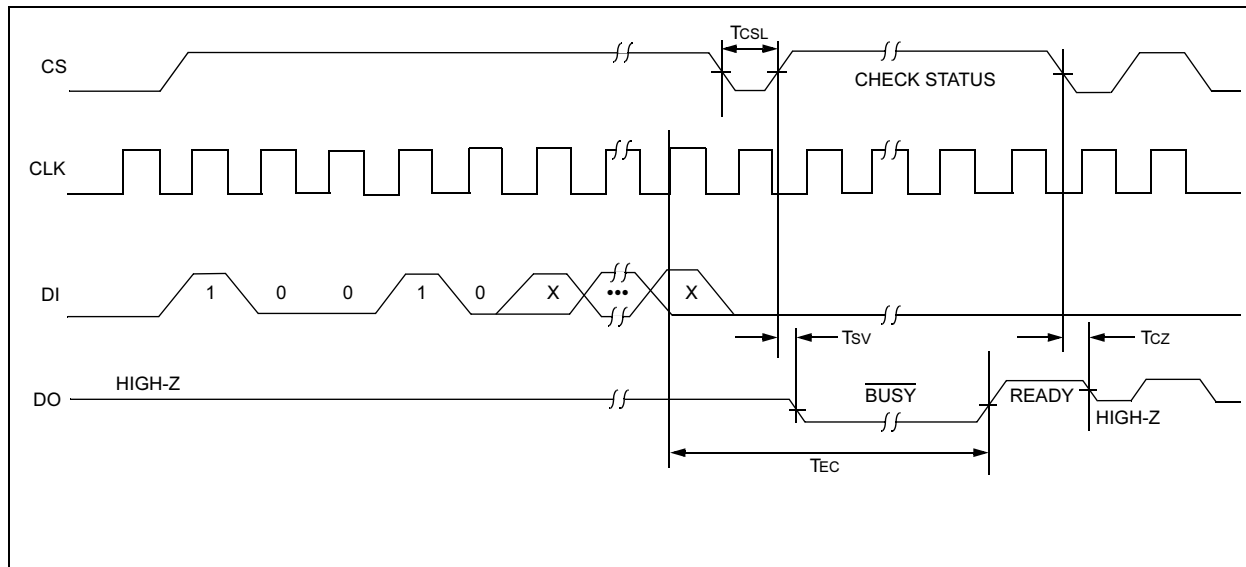


FIGURE 2-4: ERAL TIMING FOR 93C DEVICES



93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

2.6 ERASE/WRITE DISABLE And ENABLE (EWDS/EWEN)

The 93XX66A/B/C powers up in the ERASE/WRITE Disable (EWDS) state. All Programming modes must be preceded by an ERASE/WRITE Enable (EWEN) instruction. Once the EWEN instruction is executed, programming remains enabled until an EWDS instruction is executed or Vcc is removed from the device. To protect

against accidental data disturbance, the EWDS instruction can be used to disable all ERASE/WRITE functions and should follow all programming operations. Execution of a READ instruction is independent of both the EWEN and EWDS instructions.

FIGURE 2-5: EWDS TIMING

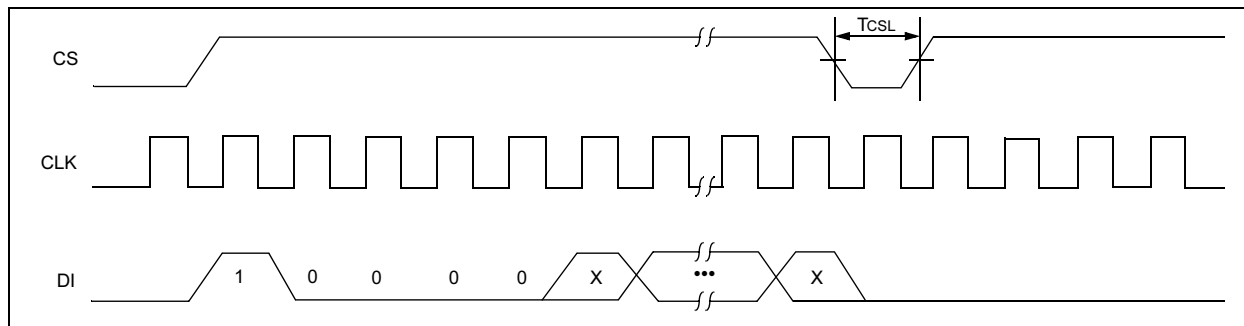
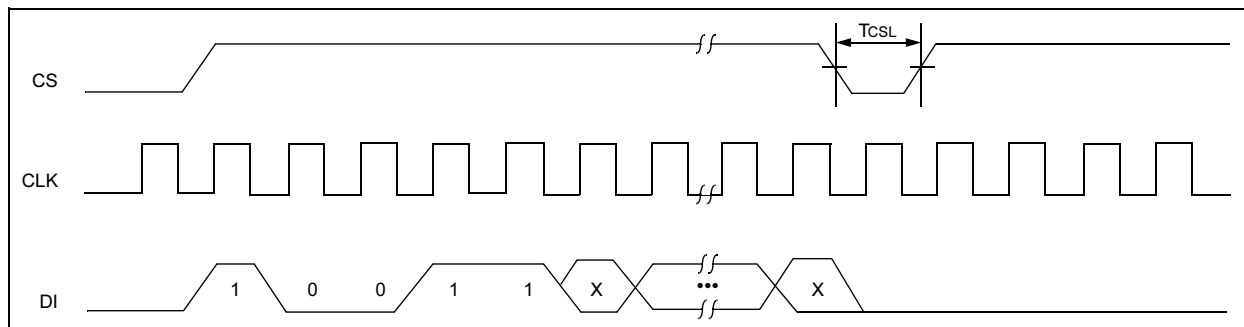


FIGURE 2-6: EWEN TIMING

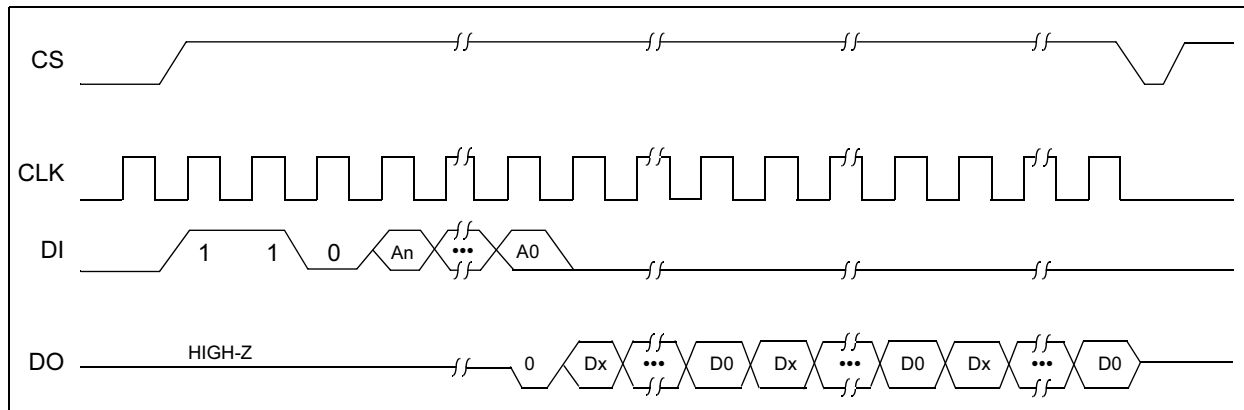


2.7 READ

The READ instruction outputs the serial data of the addressed memory location on the DO pin. A dummy zero bit precedes the 8-bit (If ORG pin is low or A-Version devices) or 16-bit (If ORG pin is high or B-version

devices) output string. The output data bits will toggle on the rising edge of the CLK and are stable after the specified time delay (TPD). Sequential read is possible when CS is held high. The memory data will automatically cycle to the next register and output sequentially.

FIGURE 2-7: READ TIMING



93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

2.8 WRITE

The **WRITE** instruction is followed by 8 bits (If **ORG** is low or A-version devices) or 16 bits (If **ORG** pin is high or B-version devices) of data which are written into the specified address. For 93AA66A/B/C and 93LC66A/B/C devices, after the last data bit is clocked into **DI**, the falling edge of **CS** initiates the self-timed auto-erase and programming cycle. For 93C66A/B/C devices, the self-timed auto-erase and programming cycle is initiated by the rising edge of **CLK** on the last data bit.

The **DO** pin indicates the **READY/BUSY** status of the device, if **CS** is brought high after a minimum of 250 ns low (T_{CSL}). **DO** at logical "0" indicates that programming is still in progress. **DO** at logical "1" indicates that the register at the specified address has been written with the data specified and the device is ready for another instruction.

Note: Issuing a **START** bit and then taking **CS** low will clear the **READY/BUSY** status from **DO**.

FIGURE 2-8: WRITE TIMING FOR 93AA AND 93LC DEVICES

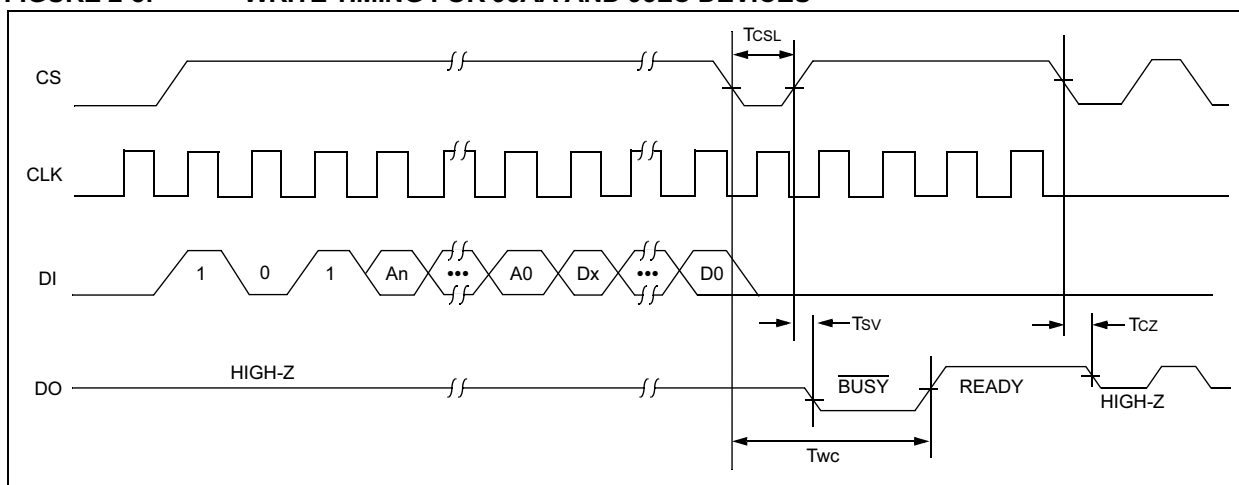
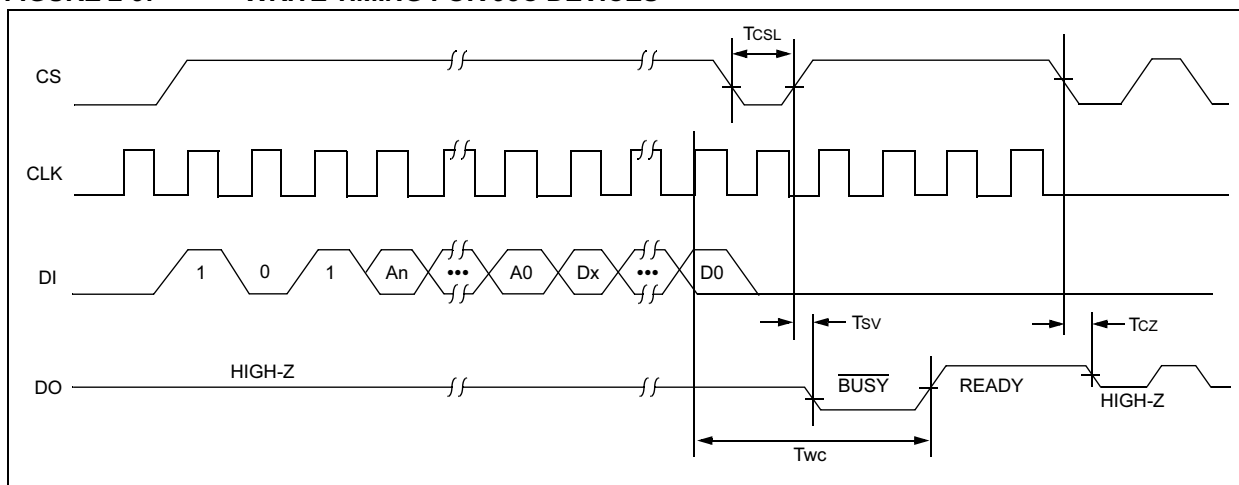


FIGURE 2-9: WRITE TIMING FOR 93C DEVICES



93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

2.9 WRITE ALL (WRAL)

The Write All (WRAL) instruction will write the entire memory array with the data specified in the command. For 93AA66A/B/C and 93LC66A/B/C devices, after the last data bit is clocked into DI, the falling edge of CS initiates the self-timed auto-erase and programming cycle. For 93C66A/B/C devices, the self-timed auto-erase and programming cycle is initiated by the rising edge of CLK on the last data bit. Clocking of the CLK pin is not necessary after the device has entered the WRAL cycle. The WRAL command does include an

automatic ERAL cycle for the device. Therefore, the WRAL instruction does not require an ERAL instruction but the chip must be in the EWEN status.

The DO pin indicates the READY/BUSY status of the device if CS is brought high after a minimum of 250 ns low (T_{CSL}).

Note: Issuing a START bit and then taking CS low will clear the READY/BUSY status from DO.

V_{CC} must be $\geq 4.5V$ for proper operation of WRAL.

FIGURE 2-10: WRAL TIMING FOR 93AA AND 93LC DEVICES

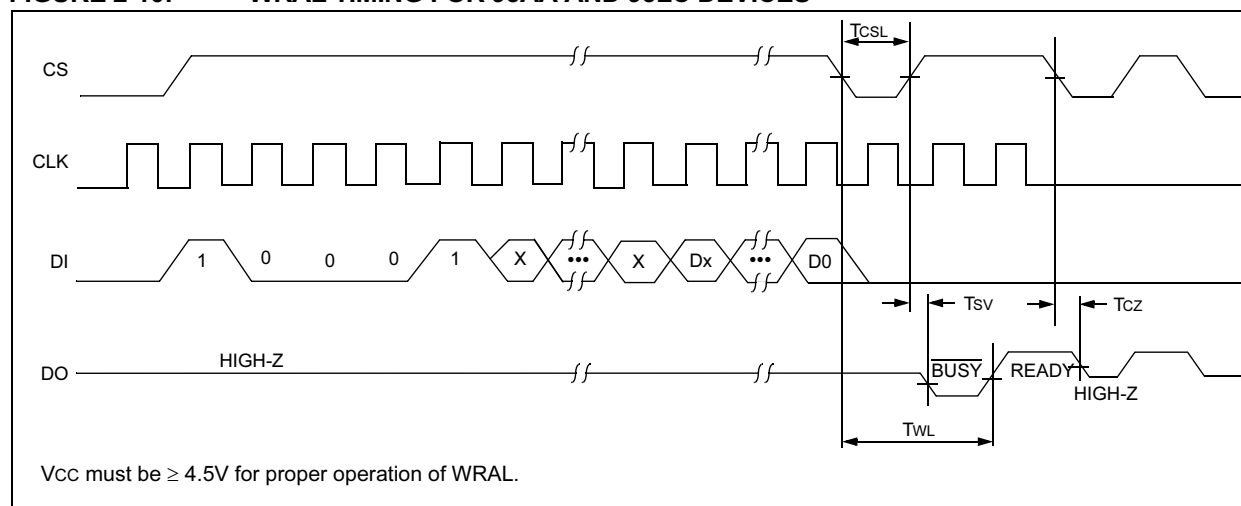
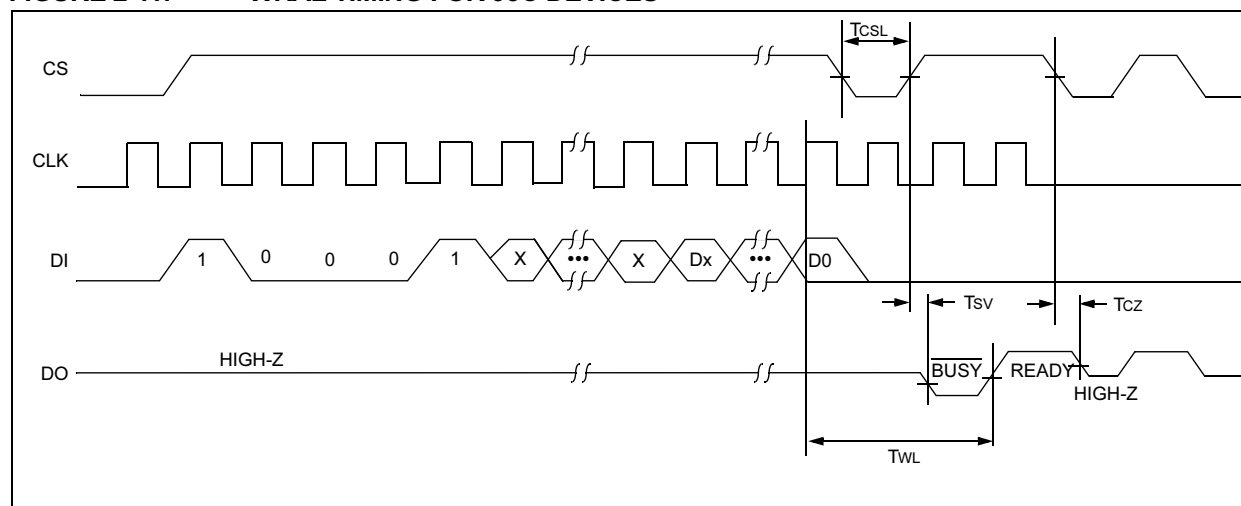


FIGURE 2-11: WRAL TIMING FOR 93C DEVICES



93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

3.0 PIN DESCRIPTIONS

TABLE 3-1: PIN DESCRIPTIONS

| Name | SOIC/PDIP/ MSOP/TSSOP | SOT-23 | Rotated SOIC | Function |
|--------|--------------------------|--------|--------------|--|
| CS | 1 | 5 | 3 | Chip Select |
| CLK | 2 | 4 | 4 | Serial Clock |
| DI | 3 | 3 | 5 | Data In |
| DO | 4 | 1 | 6 | Data Out |
| Vss | 5 | 2 | 7 | Ground |
| ORG/NC | 6 | N/A | 8 | Organization / 93XX66C No Internal Connection / 93XX66A/B |
| NC | 7 | N/A | 1 | No Internal Connection |
| Vcc | 8 | 6 | 2 | Power Supply |

3.1 Chip Select (CS)

A high level selects the device; a low level deselects the device and forces it into Standby mode. However, a programming cycle which is already in progress will be completed, regardless of the Chip Select (CS) input signal. If CS is brought low during a program cycle, the device will go into Standby mode as soon as the programming cycle is completed.

CS must be low for 250 ns minimum (TCSL) between consecutive instructions. If CS is low, the internal control logic is held in a RESET status.

3.2 Serial Clock (CLK)

The Serial Clock is used to synchronize the communication between a master device and the 93XX series device. Opcodes, address and data bits are clocked in on the positive edge of CLK. Data bits are also clocked out on the positive edge of CLK.

CLK can be stopped anywhere in the transmission sequence (at high or low level) and can be continued anytime with respect to clock high time (TCKH) and clock low time (TCKL). This gives the controlling master freedom in preparing opcode, address and data.

CLK is a "Don't Care" if CS is low (device deselected). If CS is high, but the START condition has not been detected (DI = 0), any number of clock cycles can be received by the device without changing its status (i.e., waiting for a START condition).

CLK cycles are not required during the self-timed WRITE (i.e., auto ERASE/WRITE) cycle.

After detection of a START condition the specified number of clock cycles (respectively low to high transitions of CLK) must be provided. These clock cycles are required to clock in all required opcode, address and data bits before an instruction is executed. CLK and DI then become don't care inputs waiting for a new START condition to be detected.

3.3 Data In (DI)

Data In (DI) is used to clock in a START bit, opcode, address and data synchronously with the CLK input.

3.4 Data Out (DO)

Data Out (DO) is used in the READ mode to output data synchronously with the CLK input (TPD after the positive edge of CLK).

This pin also provides READY/BUSY status information during ERASE and WRITE cycles. READY/BUSY status information is available on the DO pin if CS is brought high after being low for minimum chip select low time (TCSL) and an ERASE or WRITE operation has been initiated.

The status signal is not available on DO, if CS is held low during the entire ERASE or WRITE cycle. In this case, DO is in the HIGH-Z mode. If status is checked after the ERASE/WRITE cycle, the data line will be high to indicate the device is ready.

Note: Issuing a START bit and then taking CS low will clear the READY/BUSY status from DO.

3.5 Organization (ORG)

When the ORG pin is connected to Vcc or Logic HI, the (x16) memory organization is selected. When the ORG pin is tied to Vss or Logic LO, the (x8) memory organization is selected. For proper operation, ORG must be tied to a valid logic level.

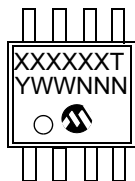
93XX66A devices are always x8 organization and 93XX66B devices are always x16 organization.

93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

4.0 PACKAGING INFORMATION

4.1 Package Marking Information

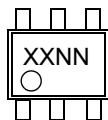
8-Lead MSOP (150 mil)



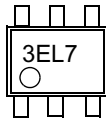
Example:



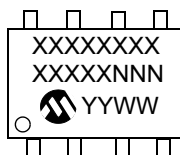
6-Lead SOT-23



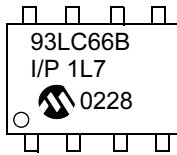
Example:



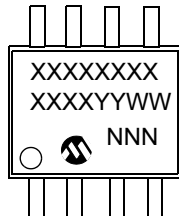
8-Lead PDIP



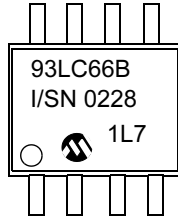
Example:



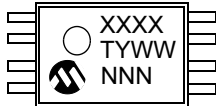
8-Lead SOIC



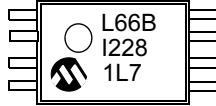
Example:



8-Lead TSSOP



Example:



MSOP 1st Line Marking Codes

| Device | std mark | Pb-free mark |
|---------|----------|--------------|
| 93AA66A | 3A66AT | GA66AT |
| 93AA66B | 3A66BT | GA66BT |
| 93AA66C | 3A66CT | GA66CT |
| 93LC66A | 3L66AT | GL66AT |
| 93LC66B | 3L66BT | GL66BT |
| 93LC66C | 3L66CT | GL66CT |
| 93C66A | 3C66AT | GC66AT |
| 93C66B | 3C66BT | GC66BT |
| 93C66C | 3C66CT | GC66CT |

T = blank for commercial, "I" for Industrial, "E" for Extended.

SOT23 Marking Codes

| Device | I-temp | E-temp |
|---------|--------|--------|
| 93AA66A | 3BNN | — |
| 93AA66B | 3LNN | — |
| 93LC66A | 3ENN | 3FNN |
| 93LC66B | 3PNN | 3RNN |
| 93C66A | 3HNN | 3JNN |
| 93C66B | 3TNN | 3UNN |

Pb-free topside mark is same; Pb-free noted only on carton label.

TSSOP 1st Line Marking Codes

| Device | std mark | Pb-free mark |
|---------|----------|--------------|
| 93AA66A | A66A | GACA |
| 93AA66B | A66B | GACB |
| 93AA66C | A66C | GACC |
| 93LC66A | L66A | GLCA |
| 93LC66B | L66B | GLCB |
| 93LC66C | L66C | GLCC |
| 93C66A | C66A | GCCA |
| 93C66B | C66B | GCCB |
| 93C66C | C66C | GCCC |

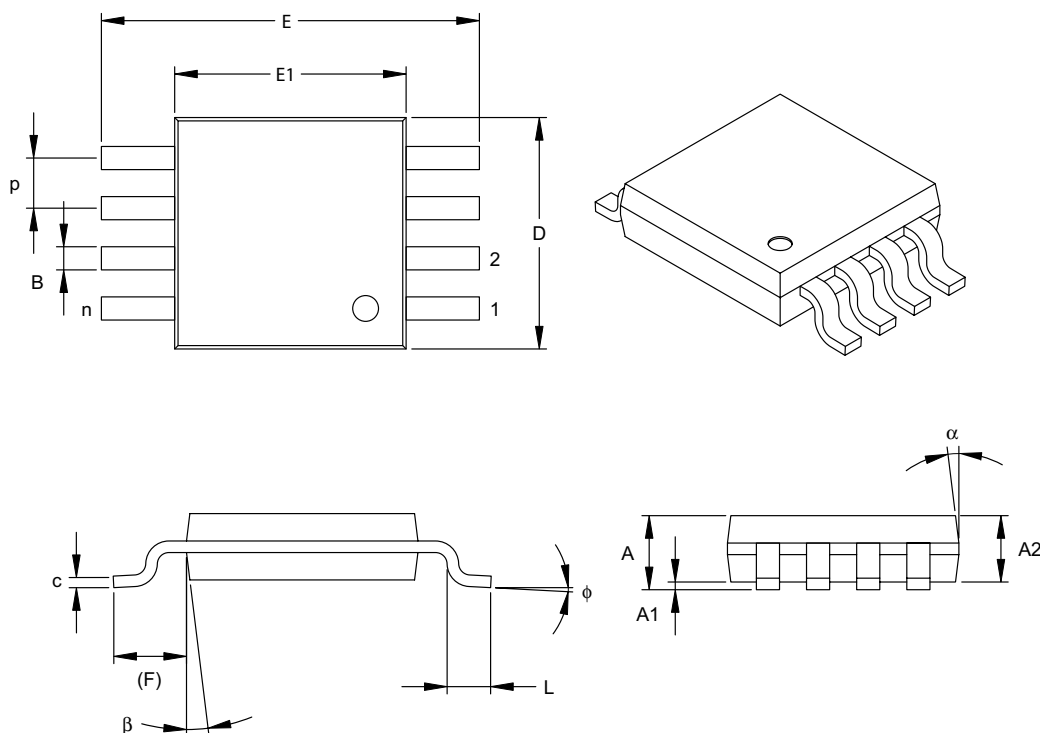
Temperature grade is marked on line 2.

| | | |
|----------------|--------|--|
| Legend: | XX...X | Part number |
| | T | Temperature |
| | Blank | Commercial |
| | I | Industrial |
| | E | Extended |
| | YY | Year code (last 2 digits of calendar year) except TSSOP and MSOP which use only the last 1 digit |
| | WW | Week code (week of January 1 is week '01') |
| | NNN | Alphanumeric traceability code |

Note: Custom marking available.

93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

8-Lead Plastic Micro Small Outline Package (MS) (MSOP)



| Units | | INCHES | | | MILLIMETERS* | | |
|--------------------------|----|-----------|------|------|--------------|------|------|
| Dimension Limits | | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | 8 | | | 8 | | |
| Pitch | p | .026 BSC | | | 0.65 BSC | | |
| Overall Height | A | - | - | .043 | - | - | 1.10 |
| Molded Package Thickness | A2 | .030 | .033 | .037 | 0.75 | 0.85 | 0.95 |
| Standoff | A1 | .000 | - | .006 | 0.00 | - | 0.15 |
| Overall Width | E | .193 TYP. | | | 4.90 BSC | | |
| Molded Package Width | E1 | .118 BSC | | | 3.00 BSC | | |
| Overall Length | D | .118 BSC | | | 3.00 BSC | | |
| Foot Length | L | .016 | .024 | .031 | 0.40 | 0.60 | 0.80 |
| Footprint (Reference) | F | .037 REF | | | 0.95 REF | | |
| Foot Angle | φ | 0° | - | 8° | 0° | - | 8° |
| Lead Thickness | c | .003 | .006 | .009 | 0.08 | - | 0.23 |
| Lead Width | B | .009 | .012 | .016 | 0.22 | - | 0.40 |
| Mold Draft Angle Top | α | 5° | - | 15° | 5° | - | 15° |
| Mold Draft Angle Bottom | β | 5° | - | 15° | 5° | - | 15° |

*Controlling Parameter

Notes:

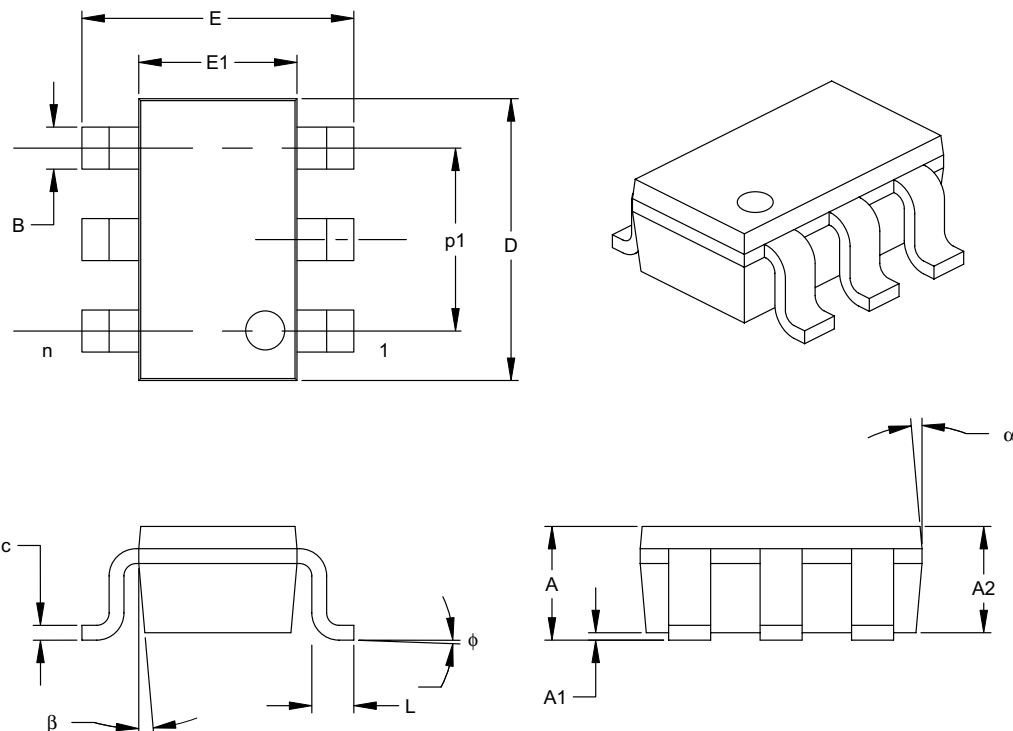
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-187

Drawing No. C04-111

93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

6-Lead Plastic Small Outline Transistor (CH) (SOT-23)



| Units | | INCHES* | | | MILLIMETERS | | |
|----------------------------|-------|---------|------|------|-------------|------|------|
| Dimension Limits | | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | | 6 | | | 6 | |
| Pitch | p | | .038 | | | 0.95 | |
| Outside lead pitch (basic) | p1 | | .075 | | | 1.90 | |
| Overall Height | A | .035 | .046 | .057 | 0.90 | 1.18 | 1.45 |
| Molded Package Thickness | A2 | .035 | .043 | .051 | 0.90 | 1.10 | 1.30 |
| Standoff | A1 | .000 | .003 | .006 | 0.00 | 0.08 | 0.15 |
| Overall Width | E | .102 | .110 | .118 | 2.60 | 2.80 | 3.00 |
| Molded Package Width | E1 | .059 | .064 | .069 | 1.50 | 1.63 | 1.75 |
| Overall Length | D | .110 | .116 | .122 | 2.80 | 2.95 | 3.10 |
| Foot Length | L | .014 | .018 | .022 | 0.35 | 0.45 | 0.55 |
| Foot Angle | phi | 0 | 5 | 10 | 0 | 5 | 10 |
| Lead Thickness | c | .004 | .006 | .008 | 0.09 | 0.15 | 0.20 |
| Lead Width | B | .014 | .017 | .020 | 0.35 | 0.43 | 0.50 |
| Mold Draft Angle Top | alpha | 0 | 5 | 10 | 0 | 5 | 10 |
| Mold Draft Angle Bottom | beta | 0 | 5 | 10 | 0 | 5 | 10 |

*Controlling Parameter

Notes:

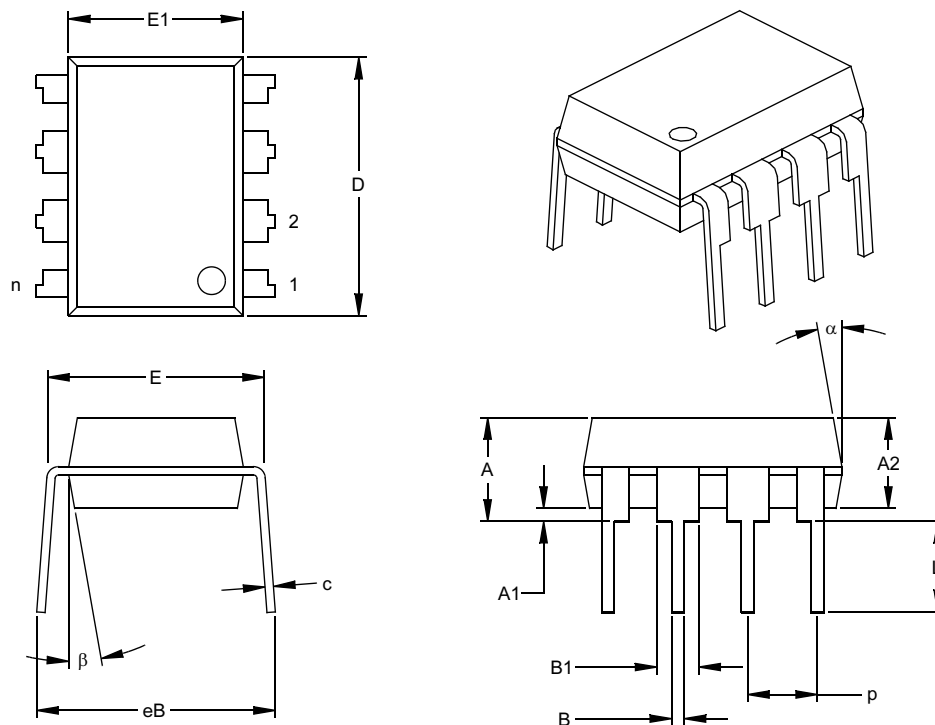
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEITA (formerly EIAJ) equivalent: SC-74A

Drawing No. C04-120

93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)



| Units | | INCHES* | | | MILLIMETERS | | |
|----------------------------|------|---------|------|------|-------------|------|-------|
| Dimension Limits | | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | | 8 | | | 8 | |
| Pitch | p | | .100 | | | 2.54 | |
| Top to Seating Plane | A | .140 | .155 | .170 | 3.56 | 3.94 | 4.32 |
| Molded Package Thickness | A2 | .115 | .130 | .145 | 2.92 | 3.30 | 3.68 |
| Base to Seating Plane | A1 | .015 | | | 0.38 | | |
| Shoulder to Shoulder Width | E | .300 | .313 | .325 | 7.62 | 7.94 | 8.26 |
| Molded Package Width | E1 | .240 | .250 | .260 | 6.10 | 6.35 | 6.60 |
| Overall Length | D | .360 | .373 | .385 | 9.14 | 9.46 | 9.78 |
| Tip to Seating Plane | L | .125 | .130 | .135 | 3.18 | 3.30 | 3.43 |
| Lead Thickness | c | .008 | .012 | .015 | 0.20 | 0.29 | 0.38 |
| Upper Lead Width | B1 | .045 | .058 | .070 | 1.14 | 1.46 | 1.78 |
| Lower Lead Width | B | .014 | .018 | .022 | 0.36 | 0.46 | 0.56 |
| Overall Row Spacing | § eB | .310 | .370 | .430 | 7.87 | 9.40 | 10.92 |
| Mold Draft Angle Top | α | 5 | 10 | 15 | 5 | 10 | 15 |
| Mold Draft Angle Bottom | β | 5 | 10 | 15 | 5 | 10 | 15 |

* Controlling Parameter

§ Significant Characteristic

Notes:

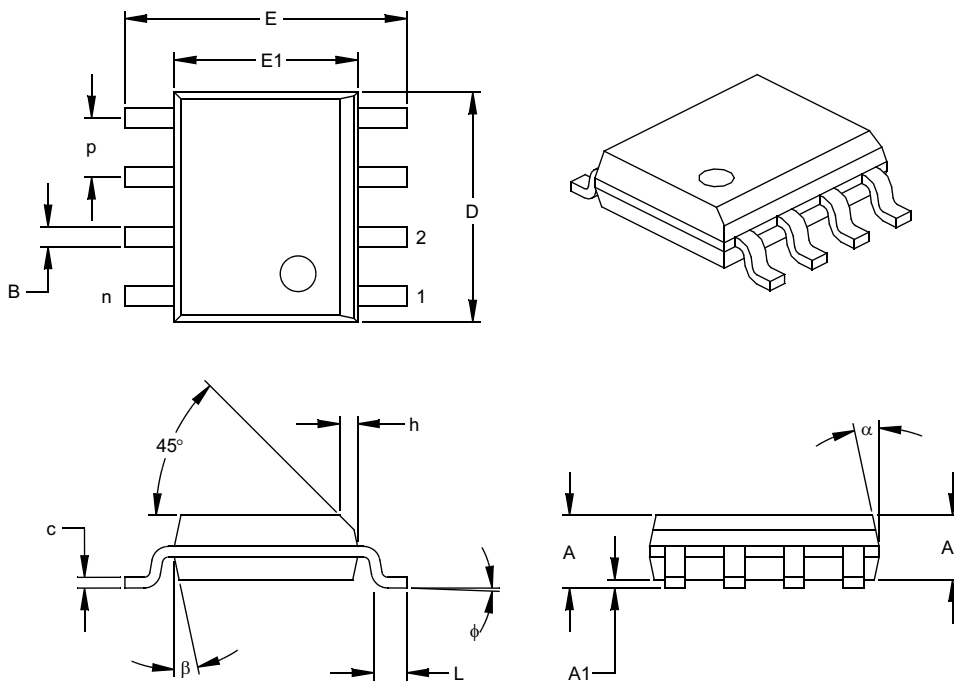
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-018

93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)



| Units | | INCHES* | | | MILLIMETERS | | |
|--------------------------|----|---------|------|------|-------------|------|------|
| Dimension Limits | | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | | 8 | | | 8 | |
| Pitch | p | | .050 | | | 1.27 | |
| Overall Height | A | .053 | .061 | .069 | 1.35 | 1.55 | 1.75 |
| Molded Package Thickness | A2 | .052 | .056 | .061 | 1.32 | 1.42 | 1.55 |
| Standoff § | A1 | .004 | .007 | .010 | 0.10 | 0.18 | 0.25 |
| Overall Width | E | .228 | .237 | .244 | 5.79 | 6.02 | 6.20 |
| Molded Package Width | E1 | .146 | .154 | .157 | 3.71 | 3.91 | 3.99 |
| Overall Length | D | .189 | .193 | .197 | 4.80 | 4.90 | 5.00 |
| Chamfer Distance | h | .010 | .015 | .020 | 0.25 | 0.38 | 0.51 |
| Foot Length | L | .019 | .025 | .030 | 0.48 | 0.62 | 0.76 |
| Foot Angle | φ | 0 | 4 | 8 | 0 | 4 | 8 |
| Lead Thickness | c | .008 | .009 | .010 | 0.20 | 0.23 | 0.25 |
| Lead Width | B | .013 | .017 | .020 | 0.33 | 0.42 | 0.51 |
| Mold Draft Angle Top | α | 0 | 12 | 15 | 0 | 12 | 15 |
| Mold Draft Angle Bottom | β | 0 | 12 | 15 | 0 | 12 | 15 |

* Controlling Parameter

§ Significant Characteristic

Notes:

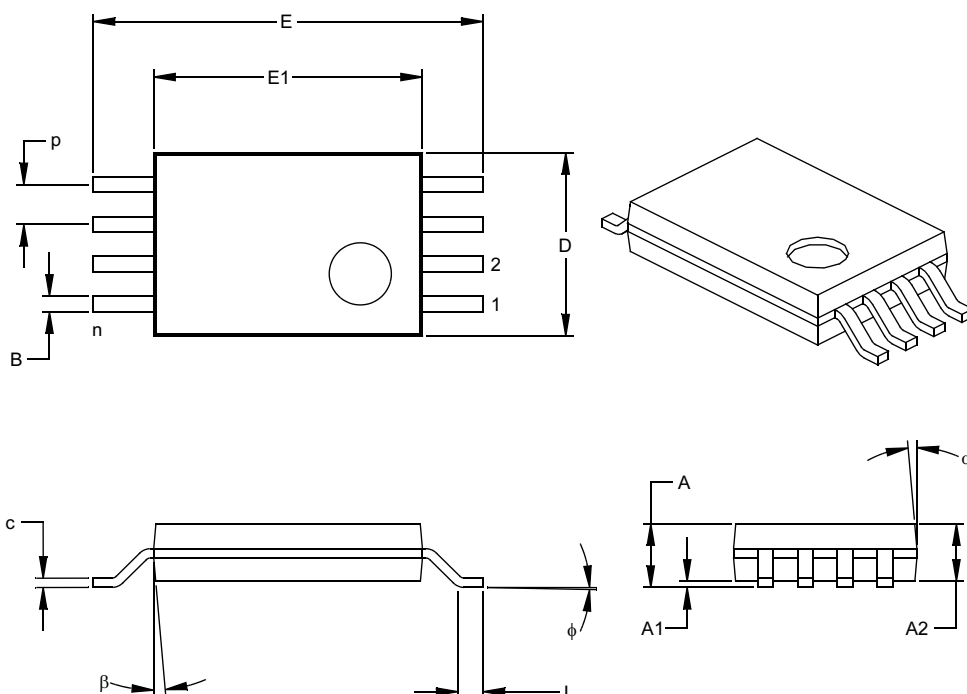
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-012

Drawing No. C04-057

93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

8-Lead Plastic Thin Shrink Small Outline (ST) – 4.4 mm (TSSOP)



| Units | | INCHES | | | MILLIMETERS* | | |
|--------------------------|----|--------|------|------|--------------|------|------|
| Dimension Limits | | MIN | NOM | MAX | MIN | NOM | MAX |
| Number of Pins | n | | 8 | | | 8 | |
| Pitch | p | | .026 | | | 0.65 | |
| Overall Height | A | | | .043 | | | 1.10 |
| Molded Package Thickness | A2 | .033 | .035 | .037 | 0.85 | 0.90 | 0.95 |
| Standoff § | A1 | .002 | .004 | .006 | 0.05 | 0.10 | 0.15 |
| Overall Width | E | .246 | .251 | .256 | 6.25 | 6.38 | 6.50 |
| Molded Package Width | E1 | .169 | .173 | .177 | 4.30 | 4.40 | 4.50 |
| Molded Package Length | D | .114 | .118 | .122 | 2.90 | 3.00 | 3.10 |
| Foot Length | L | .020 | .024 | .028 | 0.50 | 0.60 | 0.70 |
| Foot Angle | φ | 0 | 4 | 8 | 0 | 4 | 8 |
| Lead Thickness | c | .004 | .006 | .008 | 0.09 | 0.15 | 0.20 |
| Lead Width | B | .007 | .010 | .012 | 0.19 | 0.25 | 0.30 |
| Mold Draft Angle Top | α | 0 | 5 | 10 | 0 | 5 | 10 |
| Mold Draft Angle Bottom | β | 0 | 5 | 10 | 0 | 5 | 10 |

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

JEDEC Equivalent: MO-153

Drawing No. C04-086

93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

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042003

93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

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Device: 93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C Literature Number: DS21795A

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6. Is there any incorrect or misleading information (what and where)?

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93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

| <u>PART NO.</u> | <u>X</u> | <u>X</u> | <u>X</u> | <u>/XX</u> | <u>X</u> | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
|---|--|-------------|--|------------|-------------|--------|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|--|---|--|--|--|--|---|--|--|--|--|---|--|--|--|--|---------|-------|---|-----------------|--|--|---|---|----------------|--|--|--------------|-------|---|--------------------|--|--|---|---|-------------|--|--|-------------------|---|---|----------------|--|--|---|---|-----------------|--|--|---------|----|---|--|--|--|----|---|-----------------------------------|--|--|---|---|------------------------------------|--|--|----|---|-------------------------------------|--|--|----|---|---------------|--|--|--------------|-------|---|-------------------------|--|--|---|---|---------------|--|--|
| Device | Pinout | Tape & Reel | Temperature Range | Package | Lead Finish | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| <table><tr><td rowspan="3">Device</td><td colspan="5">93AA66A: 4K 1.8V Microwire Serial EEPROM</td></tr><tr><td colspan="5">93AA66B: 4K 1.8V Microwire Serial EEPROM</td></tr><tr><td colspan="5">93AA66C: 4K 1.8V Microwire Serial EEPROM w/ORG</td></tr><tr><td rowspan="3"></td><td colspan="5">93LC66A: 4K 2.5V Microwire Serial EEPROM</td></tr><tr><td colspan="5">93LC66B: 4K 2.5V Microwire Serial EEPROM</td></tr><tr><td colspan="5">93LC66C: 4K 2.5V Microwire Serial EEPROM w/ORG</td></tr><tr><td rowspan="3"></td><td colspan="5">93C66A: 4K 5.0V Microwire Serial EEPROM</td></tr><tr><td colspan="5">93C66B: 4K 5.0V Microwire Serial EEPROM</td></tr><tr><td colspan="5">93C66C: 4K 5.0V Microwire Serial EEPROM w/ORG</td></tr><tr><td rowspan="2">Pinout:</td><td>Blank</td><td>=</td><td colspan="3">Standard pinout</td></tr><tr><td>X</td><td>=</td><td colspan="3">Rotated pinout</td></tr><tr><td rowspan="2">Tape & Reel:</td><td>Blank</td><td>=</td><td colspan="3">Standard packaging</td></tr><tr><td>T</td><td>=</td><td colspan="3">Tape & Reel</td></tr><tr><td rowspan="2">Temperature Range</td><td>I</td><td>=</td><td colspan="3">-40°C to +85°C</td></tr><tr><td>E</td><td>=</td><td colspan="3">-40°C to +125°C</td></tr><tr><td rowspan="5">Package</td><td>MS</td><td>=</td><td colspan="3">Plastic MSOP (Micro Small outline, 8-lead)</td></tr><tr><td>OT</td><td>=</td><td colspan="3">SOT-23, 6-lead (Tape & Reel only)</td></tr><tr><td>P</td><td>=</td><td colspan="3">Plastic DIP (300 mil body), 8-lead</td></tr><tr><td>SN</td><td>=</td><td colspan="3">Plastic SOIC (150 mil body), 8-lead</td></tr><tr><td>ST</td><td>=</td><td colspan="3">TSSOP, 8-lead</td></tr><tr><td rowspan="2">Lead Finish:</td><td>Blank</td><td>=</td><td colspan="3">Standard 63% / 37% SnPb</td></tr><tr><td>G</td><td>=</td><td colspan="3">Pure Matte Sn</td></tr></table> | | | | | | Device | 93AA66A: 4K 1.8V Microwire Serial EEPROM | | | | | 93AA66B: 4K 1.8V Microwire Serial EEPROM | | | | | 93AA66C: 4K 1.8V Microwire Serial EEPROM w/ORG | | | | | | 93LC66A: 4K 2.5V Microwire Serial EEPROM | | | | | 93LC66B: 4K 2.5V Microwire Serial EEPROM | | | | | 93LC66C: 4K 2.5V Microwire Serial EEPROM w/ORG | | | | | | 93C66A: 4K 5.0V Microwire Serial EEPROM | | | | | 93C66B: 4K 5.0V Microwire Serial EEPROM | | | | | 93C66C: 4K 5.0V Microwire Serial EEPROM w/ORG | | | | | Pinout: | Blank | = | Standard pinout | | | X | = | Rotated pinout | | | Tape & Reel: | Blank | = | Standard packaging | | | T | = | Tape & Reel | | | Temperature Range | I | = | -40°C to +85°C | | | E | = | -40°C to +125°C | | | Package | MS | = | Plastic MSOP (Micro Small outline, 8-lead) | | | OT | = | SOT-23, 6-lead (Tape & Reel only) | | | P | = | Plastic DIP (300 mil body), 8-lead | | | SN | = | Plastic SOIC (150 mil body), 8-lead | | | ST | = | TSSOP, 8-lead | | | Lead Finish: | Blank | = | Standard 63% / 37% SnPb | | | G | = | Pure Matte Sn | | |
| Device | 93AA66A: 4K 1.8V Microwire Serial EEPROM | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | 93AA66B: 4K 1.8V Microwire Serial EEPROM | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | 93AA66C: 4K 1.8V Microwire Serial EEPROM w/ORG | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | 93LC66A: 4K 2.5V Microwire Serial EEPROM | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | 93LC66B: 4K 2.5V Microwire Serial EEPROM | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | 93LC66C: 4K 2.5V Microwire Serial EEPROM w/ORG | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | 93C66A: 4K 5.0V Microwire Serial EEPROM | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | 93C66B: 4K 5.0V Microwire Serial EEPROM | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | 93C66C: 4K 5.0V Microwire Serial EEPROM w/ORG | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Pinout: | Blank | = | Standard pinout | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | X | = | Rotated pinout | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Tape & Reel: | Blank | = | Standard packaging | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | T | = | Tape & Reel | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Temperature Range | I | = | -40°C to +85°C | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | E | = | -40°C to +125°C | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Package | MS | = | Plastic MSOP (Micro Small outline, 8-lead) | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | OT | = | SOT-23, 6-lead (Tape & Reel only) | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | P | = | Plastic DIP (300 mil body), 8-lead | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | SN | = | Plastic SOIC (150 mil body), 8-lead | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | ST | = | TSSOP, 8-lead | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| Lead Finish: | Blank | = | Standard 63% / 37% SnPb | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |
| | G | = | Pure Matte Sn | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | | |

Examples:

- a) 93AA66C-I/MS: 4K, 512x8 or 256x16 Serial EEPROM, MSOP package, 1.8V
- b) 93AA66B-I/MS: 4K, 256x16 Serial EEPROM, MSOP package, 1.8V
- c) 93AA66AT-I/OT: 4K, 512x8 Serial EEPROM, SOT-23 package, tape and reel, 1.8V
- d) 93AA66CT-I/MS: 4K, 512x8 or 256x16 Serial EEPROM, MSOP package, tape and reel, 1.8V
- a) 93LC66A-I/MS: 4K, 512x8 Serial EEPROM, MSOP package, 2.5V
- b) 93LC66BT-I/OT: 4K, 256x16 Serial EEPROM, SOT-23 package, tape and reel, 2.5V
- c) 93LC66B-I/MS: 4K, 256x16 Serial EEPROM, MSOP package, 2.5V
- d) 93LC66BXT-I/SNG: 4K, 256x16 Serial EEPROM, SOIC package, rotated pinout, Industrial temperature, Pb-free finish, 2.5V
- a) 93C66B-I/MS: 4K, 256x16 Serial EEPROM, MSOP package, 5.0V
- b) 93C66C-I/MS: 4K, 512x8 or 256x16 Serial EEPROM, MSOP package, 5.0V
- c) 93C66AT-I/OT: 4K, 512x8 Serial EEPROM, SOT-23 package, tape and reel, 5.0V

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93AA66A/B/C, 93LC66A/B/C, 93C66A/B/C

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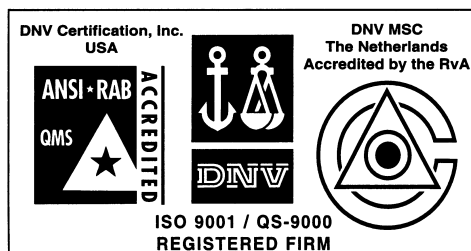
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